



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

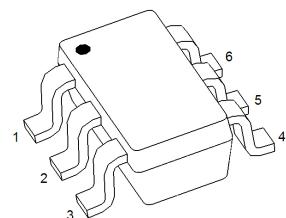
SOT-23-6 Plastic-Encapsulate MOSFETs

S8205A

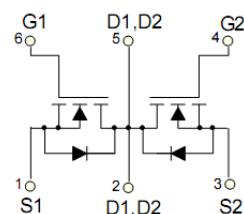
S8205A Dual N-Channel MOSFET

V_{(BR)DSS}	R_{D(on)MAX}	I_{D Max}
20V	0.022 Ω @ 4.5V	6.0A
	0.030 Ω @ 2.5V	

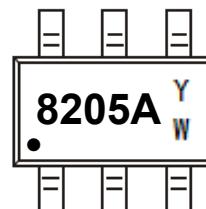
SOT-23-6



Equivalent Circuit



MARKING



Y :year code W :week code

ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±10	V
Continuous Drain Current	I _D	6	A
Pulsed Drain Current (note 1)	I _{DM}	20	A
Thermal Resistance from Junction to Ambient (note 2)	R _{θJA}	100	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~+150	°C
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T _L	260	°C



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

SOT-23-6 Plastic-Encapsulate MOSFETS

S8205A

MOSFET ELECTRICAL CHARACTERISTICS

T_a = 25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 18V, V _{GS} = 0V			500	nA
Gate-body leakage current	I _{GSS}	V _{GS} = ±10V, V _{DS} = 0V			±100	nA
Gate threshold voltage (note 3)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.5	0.7	1.0	V
Drain-source on-resistance (note 3)	R _{DS(on)}	V _{GS} = 4.5V, I _D = 5A		19	22	mΩ
		V _{GS} = 2.5V, I _D = 4A		24	30	mΩ
Forward transconductance (note 3)	g _F	V _{DS} = 5V, I _D = 5A		10		S
Diode forward voltage (note 3)	V _{SD}	I _S = 1.25A, V _{GS} = 0V			1.2	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C _{iss}	V _{DS} = 8V, V _{GS} = 0V, f = 1MHz		800		pF
Output Capacitance	C _{oss}			155		pF
Reverse Transfer Capacitance	C _{rss}			125		pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time	t _{d(on)}	V _{DD} = 10V, V _{GS} = 4V, I _D = 1A, R _{GEN} = 10Ω		18		ns
Turn-on rise time	t _r			4.8		ns
Turn-off delay time	t _{d(off)}			43.5		ns
Turn-off fall time	t _f			20		ns
Total Gate Charge	Q _g	V _{DS} = 10V, V _{GS} = 4.5V, I _D = 4A		11		nC
Gate-Source Charge	Q _{gs}			2.2		nC
Gate-Drain Charge	Q _{gd}			2.5		nC

Notes :

1. Repetitive rating: Pulse width limited by maximum junction temperature
2. Surface Mounted on FR4 board, t ≤ 10 sec.
3. Pulse test : Pulse width ≤ 300μs, duty cycle ≤ 2%.
4. Guaranteed by design, not subject to production.

SOT-23-6 Plastic-Encapsulate MOSFETs

S8205A

Typical Electrical and Thermal Characteristics

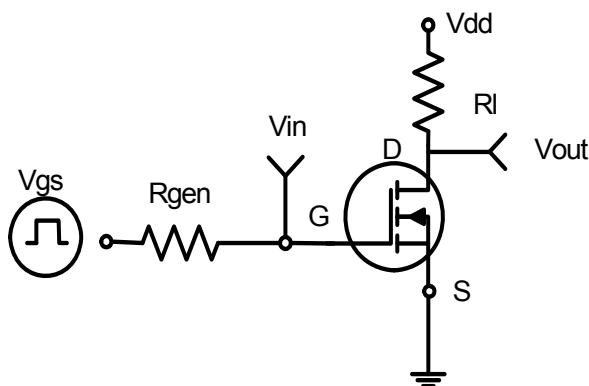


Figure 1: Switching Test Circuit

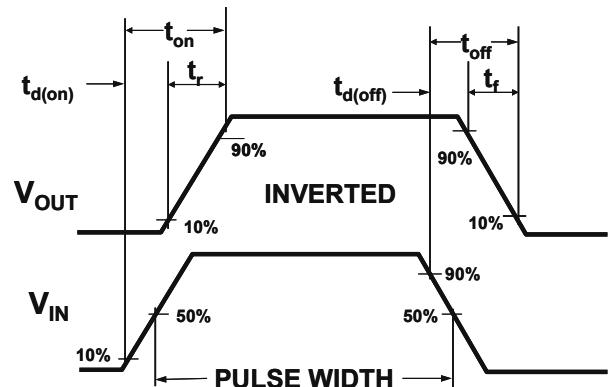


Figure 2: Switching Waveforms

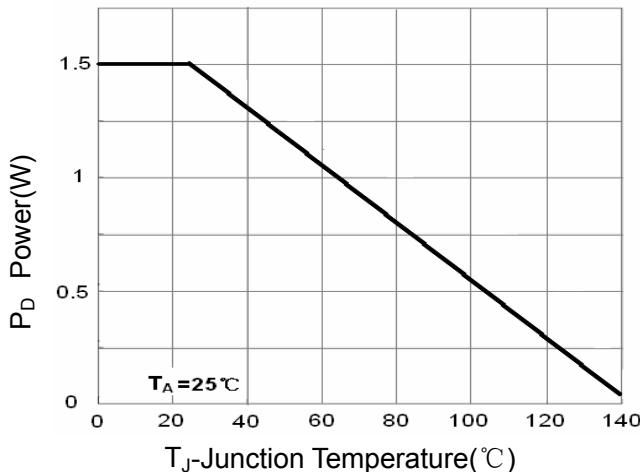


Figure 3 Power Dissipation

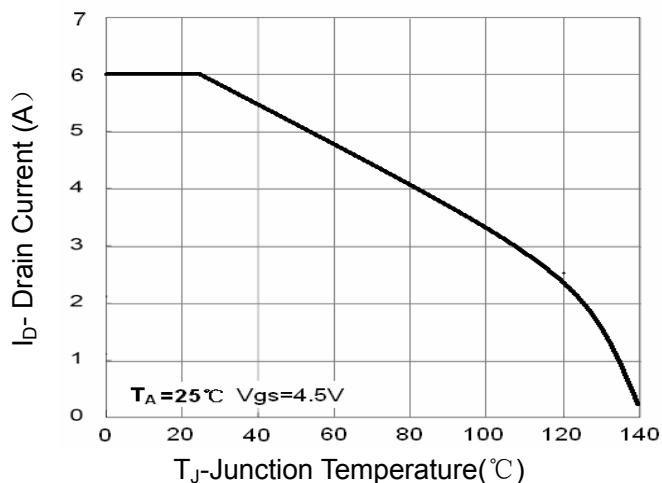


Figure 4 Drain Current

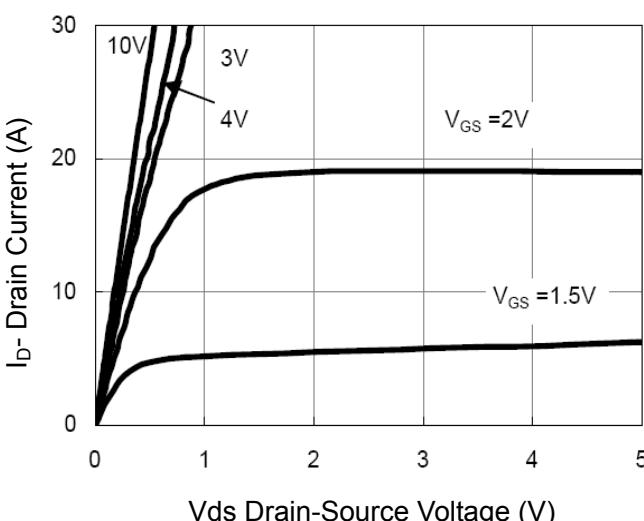


Figure 5 Output Characteristics

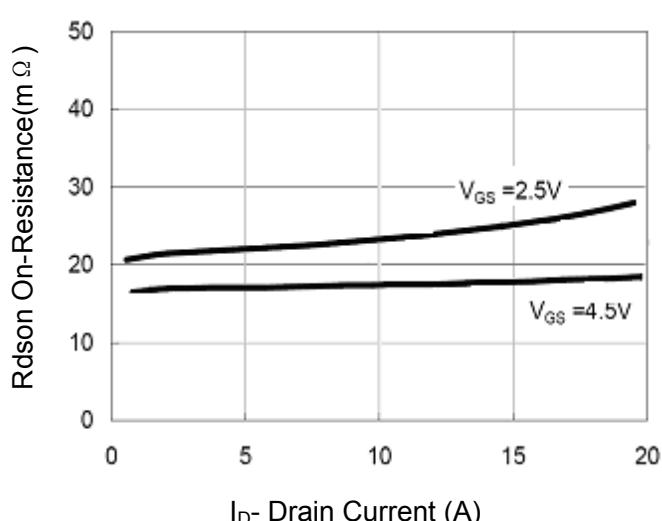


Figure 6 Drain-Source On-Resistance

SOT-23-6 Plastic-Encapsulate MOSFETs

S8205A

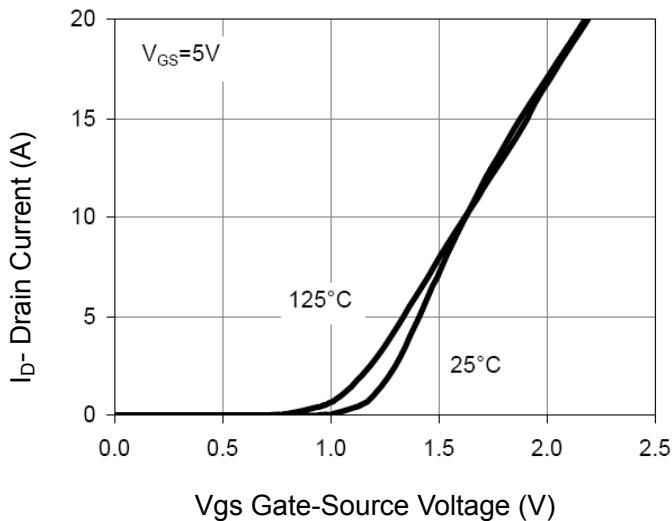


Figure 7 Transfer Characteristics

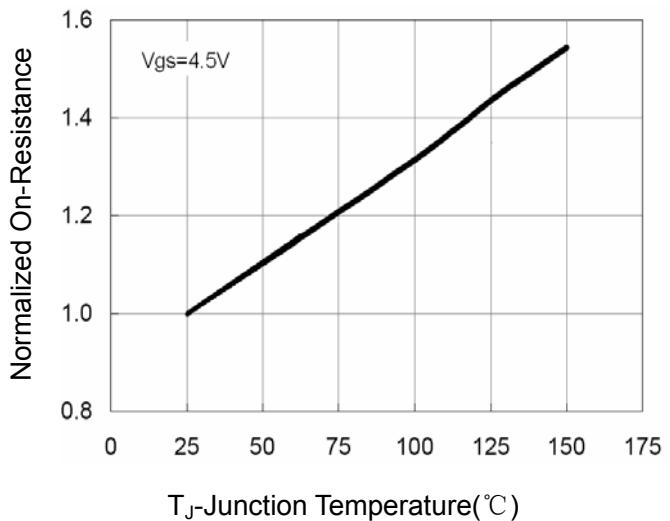


Figure 8 Drain-Source On-Resistance

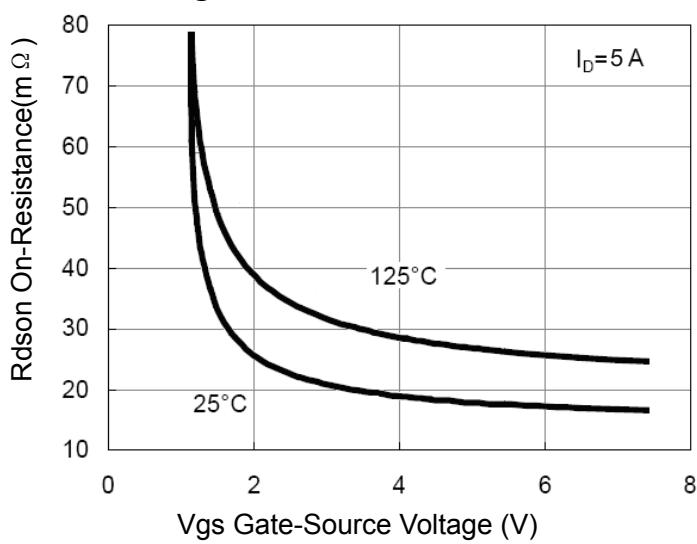


Figure 9 R_{DSON} vs V_{GS}

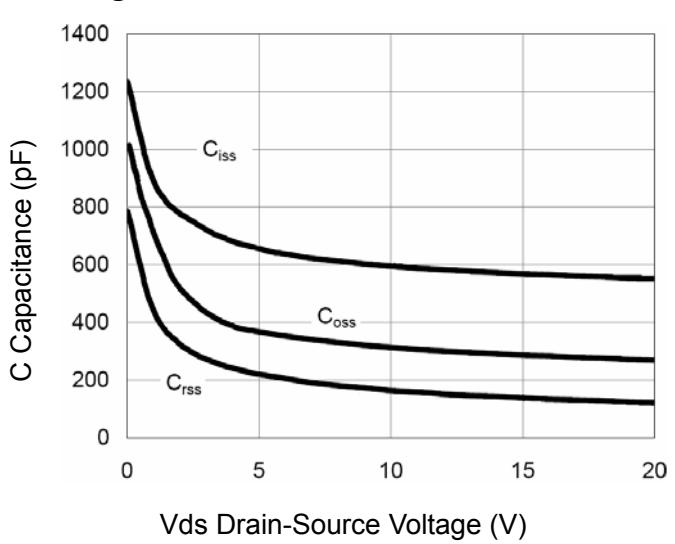


Figure 10 Capacitance vs V_{DS}

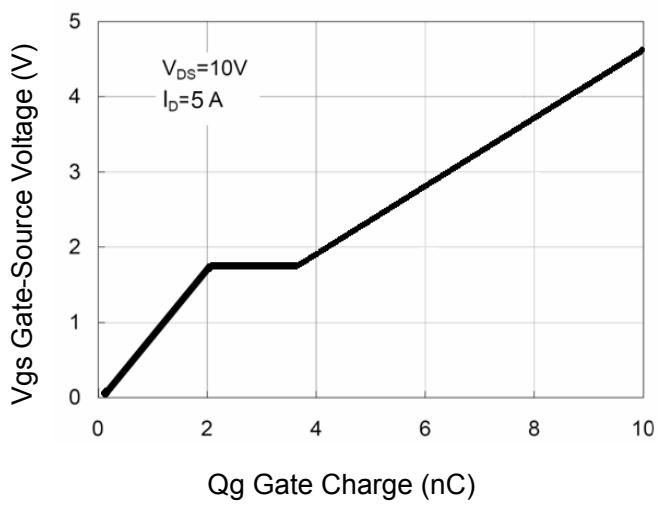


Figure 11 Gate Charge

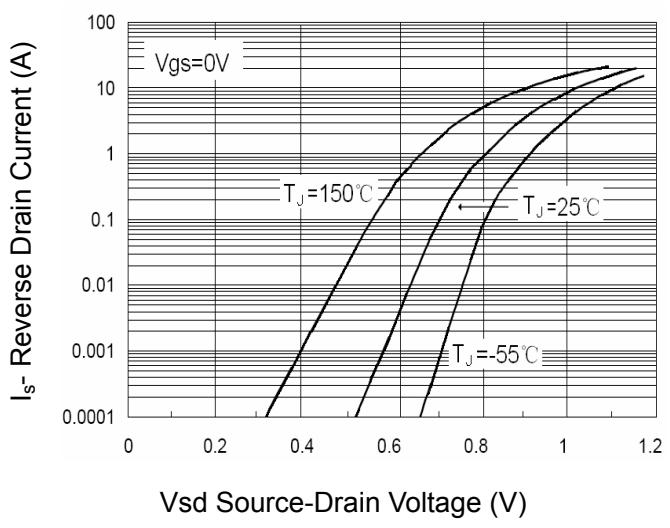


Figure 12 Source- Drain Diode Forward

SOT-23-6 Plastic-Encapsulate MOSFETs

S8205A

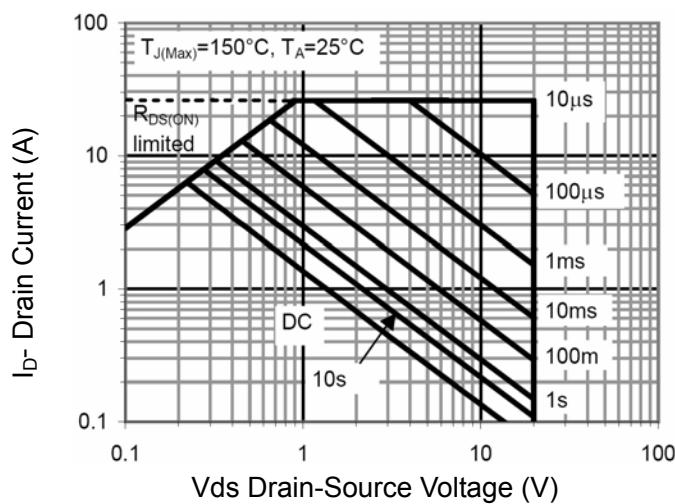


Figure 13 Safe Operation Area

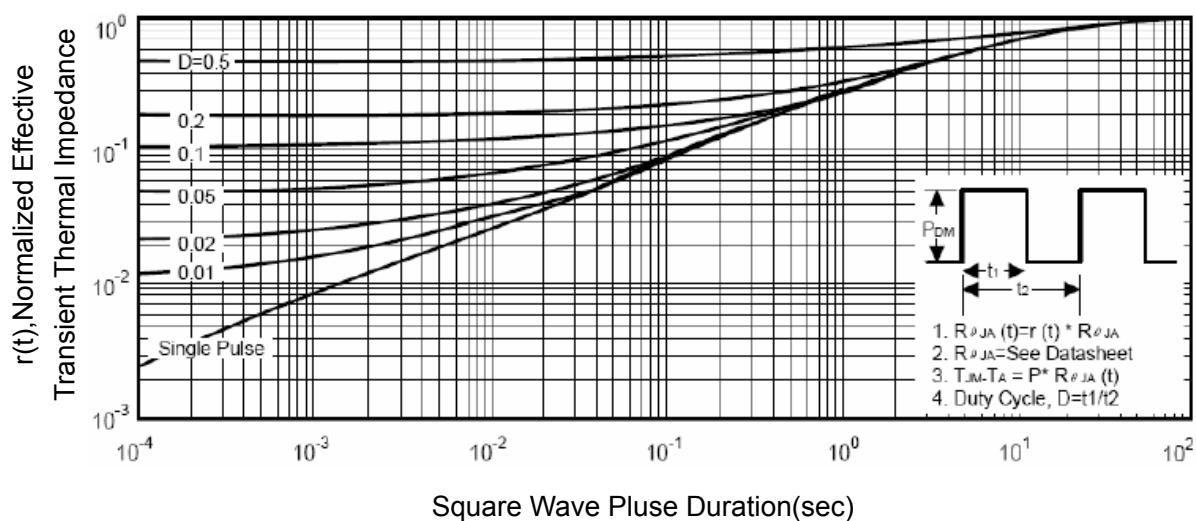


Figure 14 Normalized Maximum Transient Thermal Impedance

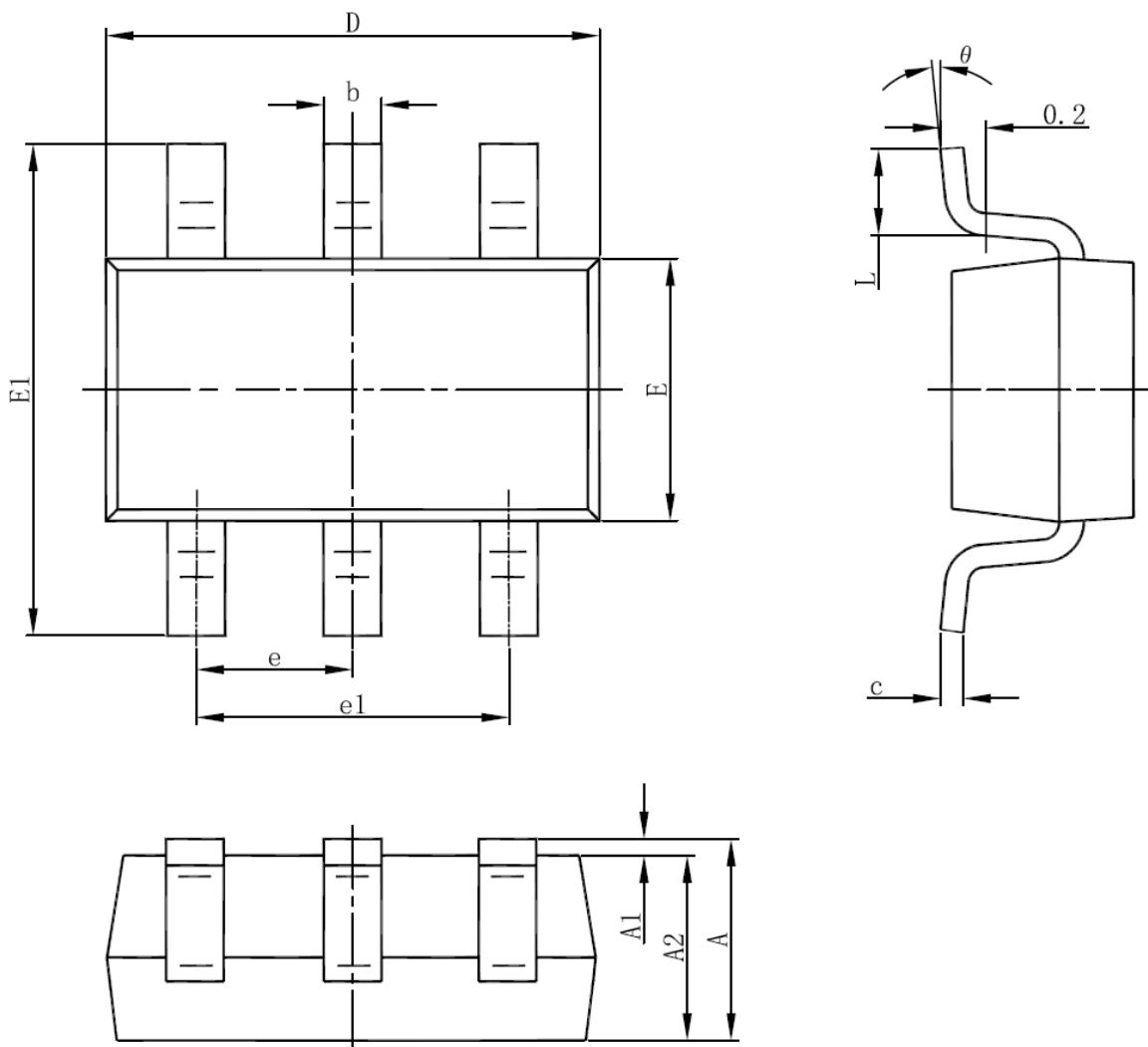


SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

SOT-23-6 Plastic-Encapsulate MOSFETs

S8205A

SOT23-6 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°